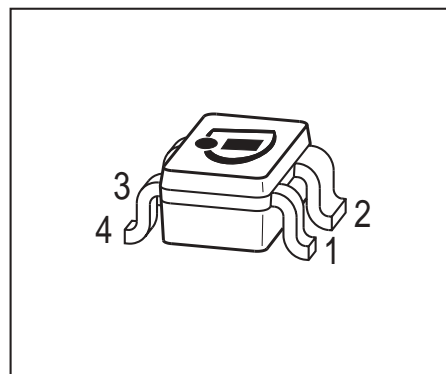


**NPN Silicon RF Transistor\***

- For low noise, high-gain amplifiers up to 2 GHz
- For linear broadband amplifiers
- $f_T = 8$  GHz,  $F = 1$  dB at 900 MHz
- \* Short term description



**ESD (Electrostatic discharge)** sensitive device, observe handling precaution!

Type	Marking	Pin Configuration						Package
BFP193W	RCs	1 = E	2 = C	3 = E	4 = B	-	-	SOT343

**Maximum Ratings**

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CEO}$	12	V
Collector-emitter voltage	$V_{CES}$	20	
Collector-base voltage	$V_{CBO}$	20	
Emitter-base voltage	$V_{EBO}$	2	
Collector current	$I_C$	80	mA
Base current	$I_B$	10	
Total power dissipation <sup>1)</sup> $T_S \leq 66^\circ\text{C}$	$P_{tot}$	580	mW
Junction temperature	$T_j$	150	$^\circ\text{C}$
Ambient temperature	$T_A$	-55 ... 150	
Storage temperature	$T_{stg}$	-55 ... 150	

**Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>2)</sup>	$R_{thJS}$	$\leq 145$	K/W

<sup>1)</sup>  $T_S$  is measured on the collector lead at the soldering point to the pcb

<sup>2)</sup> For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage $I_C = 1\text{ mA}, I_B = 0$	$V_{(BR)CEO}$	12	-	-	V
Collector-emitter cutoff current $V_{CE} = 20\text{ V}, V_{BE} = 0$	$I_{CES}$	-	-	100	$\mu\text{A}$
Collector-base cutoff current $V_{CB} = 10\text{ V}, I_E = 0$	$I_{CBO}$	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 1\text{ V}, I_C = 0$	$I_{EBO}$	-	-	1	$\mu\text{A}$
DC current gain- $I_C = 30\text{ mA}, V_{CE} = 8\text{ V}, \text{pulse measured}$	$h_{FE}$	70	100	140	-

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

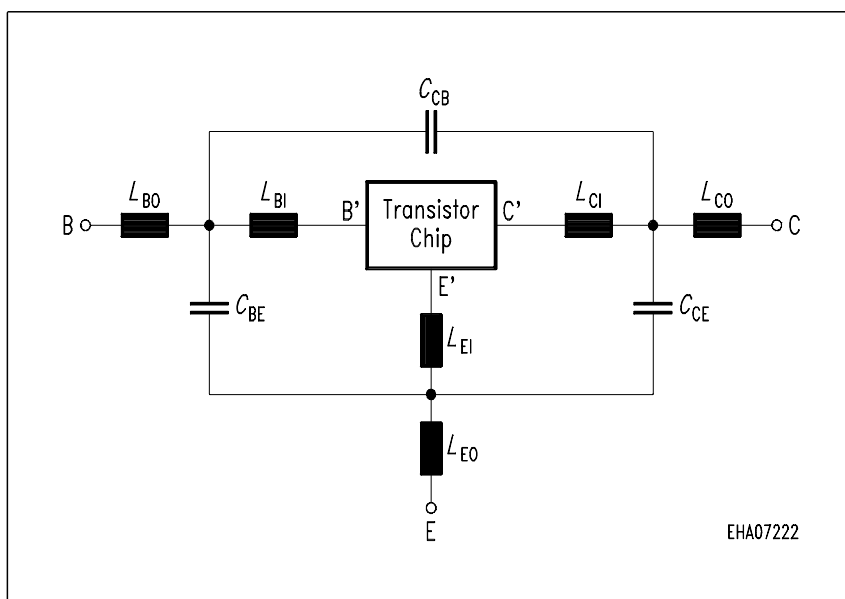
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling)					
Transition frequency $I_C = 50\text{ mA}$ , $V_{CE} = 8\text{ V}$ , $f = 500\text{ MHz}$	$f_T$	6	8	-	GHz
Collector-base capacitance $V_{CB} = 10\text{ V}$ , $f = 1\text{ MHz}$ , $V_{BE} = 0$ , emitter grounded	$C_{cb}$	-	0.63	0.9	pF
Collector emitter capacitance $V_{CE} = 10\text{ V}$ , $f = 1\text{ MHz}$ , $V_{BE} = 0$ , base grounded	$C_{ce}$	-	0.36	-	
Emitter-base capacitance $V_{EB} = 0.5\text{ V}$ , $f = 1\text{ MHz}$ , $V_{CB} = 0$ , collector grounded	$C_{eb}$	-	2.25	-	
Noise figure $I_C = 10\text{ mA}$ , $V_{CE} = 8\text{ V}$ , $Z_S = Z_{Sopt}$ , $f = 900\text{ MHz}$ $I_C = 10\text{ mA}$ , $V_{CE} = 8\text{ V}$ , $Z_S = Z_{Sopt}$ , $f = 1.8\text{ GHz}$	$F$	- -	1 1.6	- -	dB
Power gain, maximum available <sup>1)</sup> $I_C = 30\text{ mA}$ , $V_{CE} = 8\text{ V}$ , $Z_S = Z_{Sopt}$ , $Z_L = Z_{Lopt}$ , $f = 900\text{ MHz}$ $I_C = 30\text{ mA}$ , $V_{CE} = 8\text{ V}$ , $Z_S = Z_{Sopt}$ , $Z_L = Z_{Lopt}$ , $f = 1.8\text{ GHz}$	$G_{ma}$	- -	20.5 13.5	- -	
Transducer gain $I_C = 30\text{ mA}$ , $V_{CE} = 8\text{ V}$ , $Z_S = Z_L = 50\Omega$ , $f = 900\text{ MHz}$ $I_C = 30\text{ mA}$ , $V_{CE} = 8\text{ V}$ , $Z_S = Z_L = 50\Omega$ , $f = 1.8\text{ GHz}$	$ S_{21e} ^2$	- -	15 9	- -	

$$^1 G_{ma} = |S_{21} / S_{12}| (k - (k^2 - 1)^{1/2})$$

**SPICE Parameter (Gummel-Poon Model, Berkley-SPICE 2G.6 Syntax):**
**Transistor Chip Data:**

IS =	0.2738	fA	BF =	125	-	NF =	0.95341	-
VAF =	24	V	IKF =	0.26949	A	ISE =	10.627	fA
NE =	1.935	-	BR =	14.267	-	NR =	1.4289	-
VAR =	3.8742	V	IKR =	0.037925	A	ISC =	0.037409	fA
NC =	0.94371	-	RB =	1.8368	$\Omega$	IRB =	0.91763	mA
RBM =	1	$\Omega$	RE =	0.76534	-	RC =	0.11938	$\Omega$
CJE =	1.1824	fF	VJE =	0.70276	V	MJE =	0.48654	-
TF =	18.828	ps	XTF =	0.69477	-	VTF =	0.8	V
ITF =	0.96893	mA	PTF =	0	deg	CJC =	935.03	fF
VJC =	1.1828	V	MJC =	0.30002	-	XCJC =	0.053563	-
TR =	1.0037	ns	CJS =	0	fF	VJS =	0.75	V
MJS =	0	-	NK =	0	-	EG =	1.11	eV
XTI =	3	-	FC =	0.72063		TNOM	300	K

All parameters are ready to use, no scaling is necessary. Extracted on behalf of Infineon Technologies AG by:  
Institut für Mobil- und Satellitentechnik (IMST)

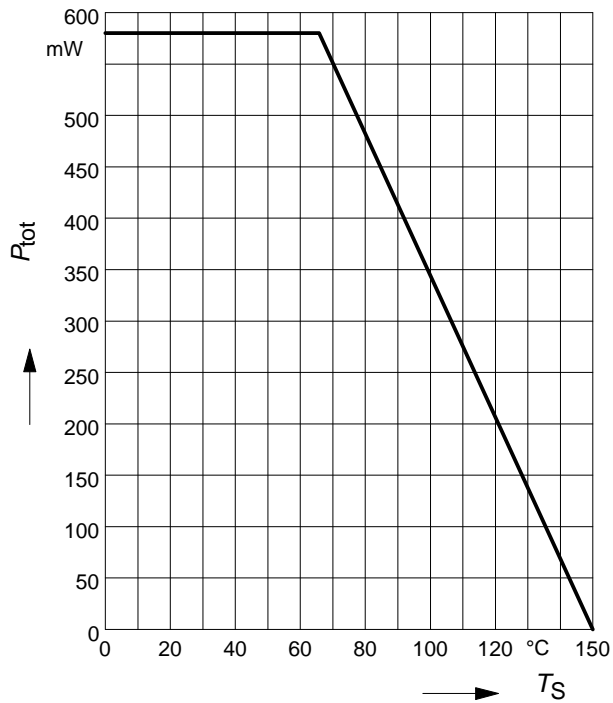
**Package Equivalent Circuit:**


$L_{BI}$ =	0.43	nH
$L_{BO}$ =	0.47	nH
$L_{EI}$ =	0.26	nH
$L_{EO}$ =	0.12	nH
$L_{CI}$ =	0.06	nH
$L_{CO}$ =	0.36	nH
$C_{BE}$ =	68	fF
$C_{CB}$ =	46	fF
$C_{CE}$ =	232	fF

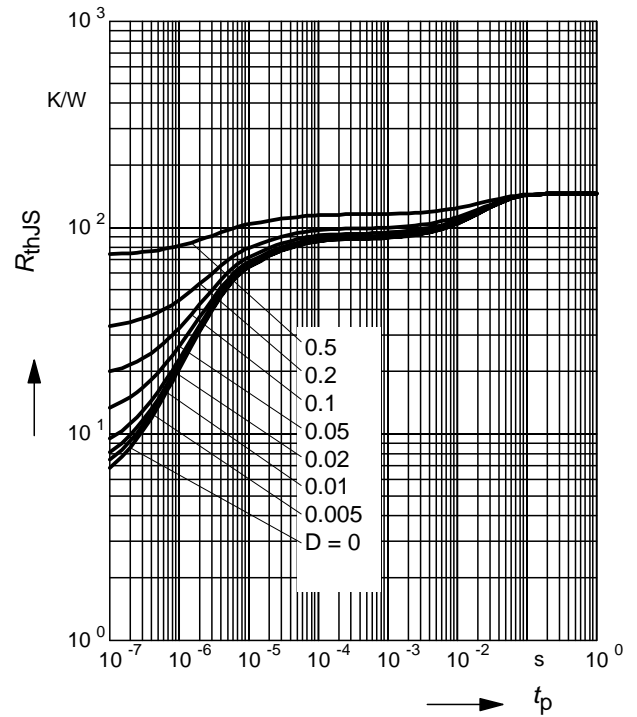
Valid up to 6GHz

For examples and ready to use parameters  
please contact your local Infineon Technologies  
distributor or sales office to obtain a Infineon  
Technologies CD-ROM or see Internet:  
<http://www.infineon.com/silicondiscretes>

Total power dissipation  $P_{\text{tot}} = f(T_S)$

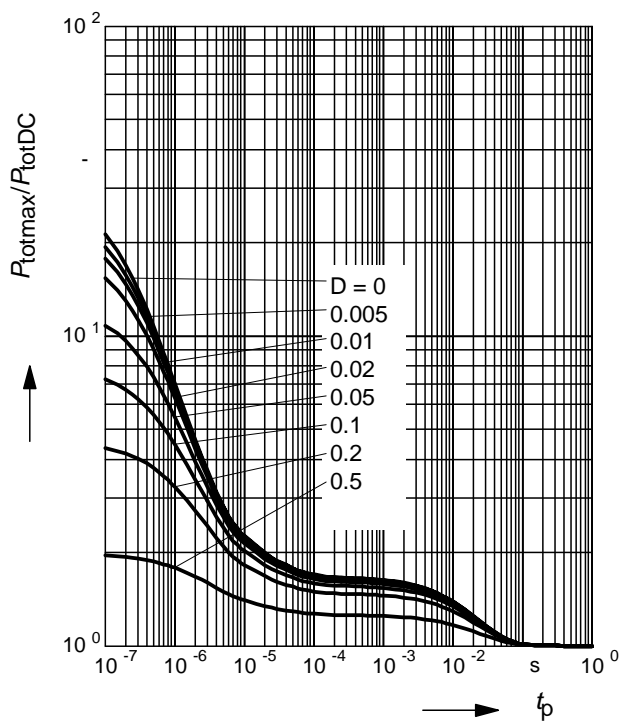


Permissible Pulse Load  $R_{\text{thJS}} = f(t_p)$

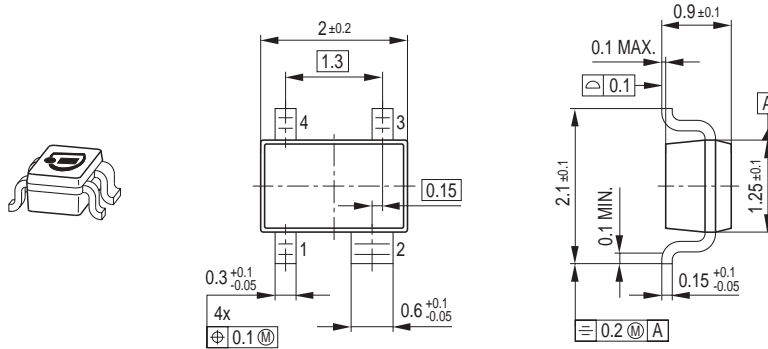


Permissible Pulse Load

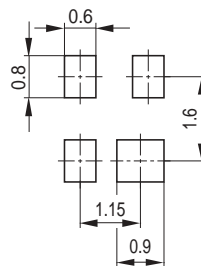
$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$



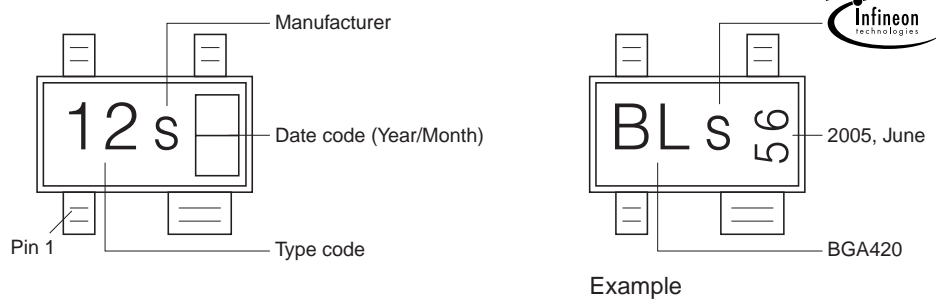
## Package Outline



## Foot Print

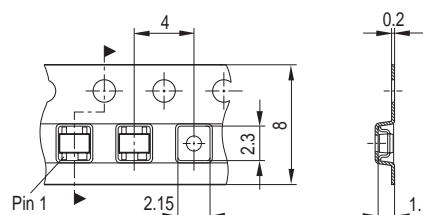


## Marking Layout



## Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel  
 Reel ø330 mm = 10.000 Pieces/Reel



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